

# EUROPEAN PATENT OFFICE

## Patent Abstracts of Japan

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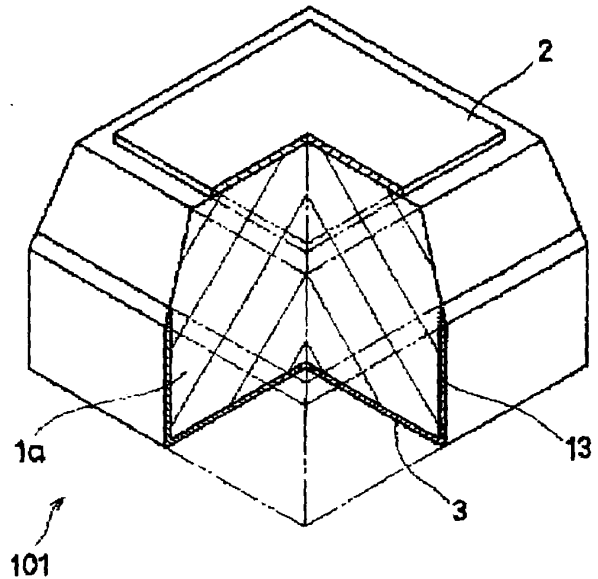
APPLICATION DATE : 27-11-92  
APPLICATION NUMBER : 04341664

APPLICANT : MITSUBISHI ELECTRIC CORP;

INVENTOR : KOBIKI MICHIIRO;

INT.CL. : H01L 21/78

TITLE : SEMICONDUCTOR DEVICE



ABSTRACT : PURPOSE: To enhance the yields of semiconductor chips, and their performance and reliability as well by avoiding the generation of broken-off or split semiconductor chips on the side with which the tip of a tweezers comes in contact as much as possible when handling the semiconductor chips with a tweezers or the like.

CONSTITUTION: A metallized layer formed on the inner surface of a wafer divided groove on the rear side of a semiconductor wafer substrate is specified as a reinforcing plating metal film 13 which protects the side of a semiconductor chip 101.

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